NICHIA CORPORATION SPECIFICATIONS FOR WHITE LED

NHSW046T

- Pb-free Reflow Soldering Application
- Built-in ESD Protection Device
- RoHS Compliant



SPECIFICATIONS

(1) Absolute Maximum Ratings

| Item | Symbol | Absolute Maximum Rating | Unit |
|---------------------------|-------------------|-------------------------|------|
| Forward Current | ${ m I}_{\sf F}$ | 10 | mA |
| Pulse Forward Current | ${ m I}_{\sf FP}$ | 30 | mA |
| Allowable Reverse Current | I_{R} | 85 | mA |
| Power Dissipation | P_{D} | 30 | mW |
| Operating Temperature | T _{opr} | -40~100 | °C |
| Storage Temperature | T_{stg} | -40~100 | °C |
| Junction Temperature | T _J | 110 | °C |

^{*} Absolute Maximum Ratings at T_A =25°C.

(2) Initial Electrical/Optical Characteristics

| Item | | Symbol | Condition | Тур | Unit |
|-------------------------|---|---------|---------------------|------|------|
| Forward Voltage | | V_{F} | I _F =5mA | 2.9 | V |
| Luminous Intensity | | I_{v} | I _F =5mA | 106 | mcd |
| | х | - | I _F =5mA | 0.31 | - |
| Chromaticity Coordinate | У | - | I _F =5mA | 0.32 | - |

^{*} Characteristics at T_A =25°C.

^{*} I_{FP} conditions with pulse width $\leq\!10\text{ms}$ and duty cycle $\leq\!10\%.$

^{*} Chromaticity Coordinates as per CIE 1931 Chromaticity Chart.

RANKS

| Item | Rank | Min | Max | Unit |
|--------------------|------|-----|-----|------|
| Forward Voltage | - | 2.7 | 3.1 | ٧ |
| | S | 125 | 180 | |
| Luminous Intensity | R | 90 | 125 | mcd |
| | Q | 63 | 90 | |

Color Ranks

| | Rank a0 | | | | |
|---|---------|-------|-------|-------|--|
| Х | 0.280 | 0.264 | 0.283 | 0.296 | |
| у | 0.248 | 0.267 | 0.305 | 0.276 | |

| | Rank b1 | | | |
|---|---------|-------|-------|-------|
| х | 0.287 | 0.283 | 0.330 | 0.330 |
| У | 0.295 | 0.305 | 0.360 | 0.339 |

| | Rank b2 | | | |
|---|---------|-------|-------|-------|
| x | 0.296 | 0.287 | 0.330 | 0.330 |
| У | 0.276 | 0.295 | 0.339 | 0.318 |

| | Rank c0 | | | | |
|---|---------|-------|-------|-------|--|
| x | 0.330 | 0.330 | 0.361 | 0.356 | |
| У | 0.318 | 0.360 | 0.385 | 0.351 | |

* Forward Voltage Tolerance: ±3%

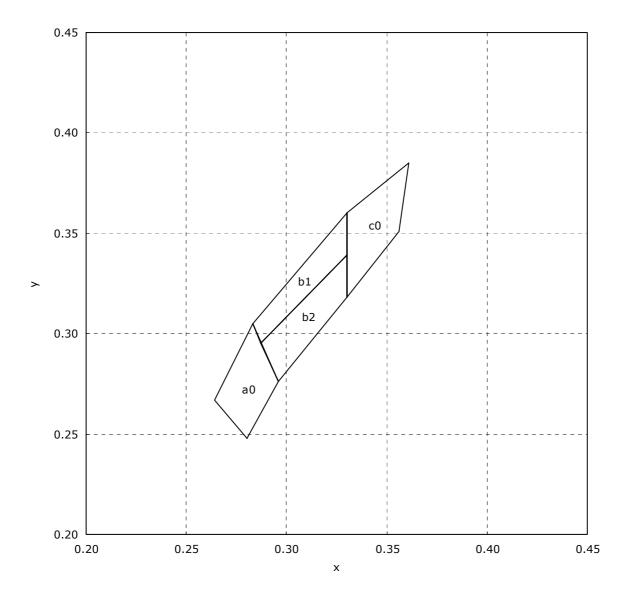
* Luminous Intensity Tolerance: ±10%

* Chromaticity Coordinate Tolerance: ±0.01

* LEDs from the above ranks will be shipped.

The rank combination ratio per shipment will be decided by Nichia.

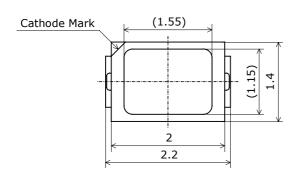
^{*} Ranking at T_A =25°C.

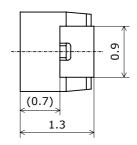


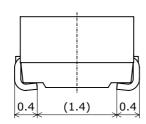
OUTLINE DIMENSIONS

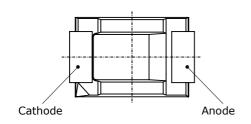
* 本製品はRoHS指令に適合しております。 This product complies with RoHS Directive. NHSx046x 管理番号 No. STS-DA7-0421A

(単位 Unit: mm, 公差 Tolerance: ±0.1)

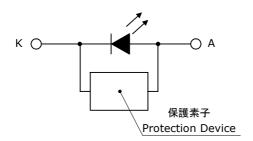






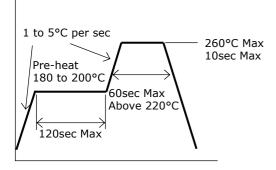


| 項目 Item | 内容 Description |
|--|--|
| パッケージ材質 Package Materials | 耐熱性ポリマー Heat-Resistant Polymer |
| 封止樹脂材質 Encapsulating Resin Materials | エポキシ樹脂 (拡散剤+蛍光体入り) Epoxy Resin (with diffuser+phosphor) |
| 電極材質 Electrodes Materials | 銅合金+銀メッキ Ag-plated Copper Alloy |
| 質量 Weight | 0.0073g(TYP) |



SOLDERING

• Recommended Reflow Soldering Condition(Lead-free Solder)



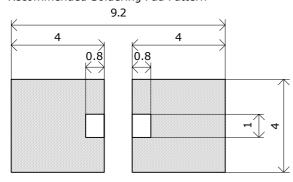
• Recommended Hand Soldering Condition

| Temperature | 350°C Max |
|----------------|-----------|
| Soldering Time | 3sec Max |

• Recommended Dip Soldering Condition

| Pre-heat | 100°C Max |
|---------------|-----------|
| Pre-heat Time | 60sec Max |
| Solder Bath | 2500014 |
| Temperature | 260°C Max |
| Dipping Time | 10sec Max |

• Recommended Soldering Pad Pattern



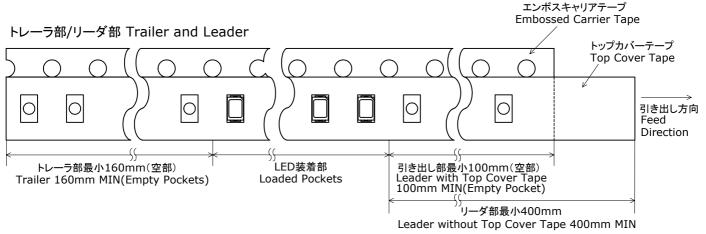
(単位 Unit: mm)

Blank boxes: Solder resist opening , Shaded areas: Footprint

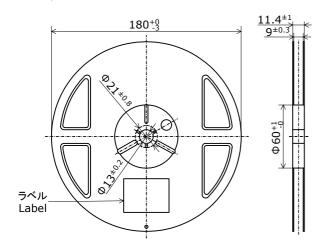
- * This LED is designed to be reflow soldered or dip-soldered on to a PCB.
- * Reflow soldering must not be performed more than twice. Dip soldering/hand soldering must not be performed more than once.
- * Avoid rapid cooling. Ramp down the temperature gradually from the peak temperature.
- * Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.
- * Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used.
 - It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- * When soldering, do not apply stress to the LED while the LED is hot.

TAPE AND REEL DIMENSIONS

テーピング部 Tape 管理番号 No. STS-DA7-0164 (単位 Unit: mm)



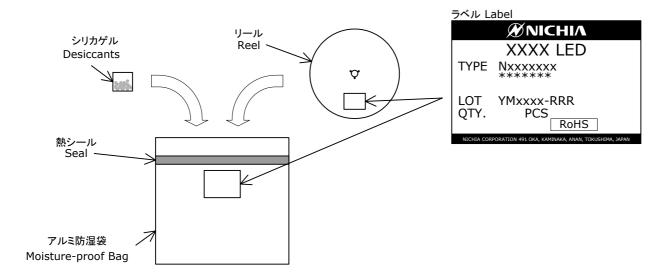
リール部 Reel



- * 数量は1リールにつき 3000個入りです。 Quantity per reel=3000pcs
- * JIS C 0806電子部品テーピングに準拠しています。
 The tape packing method complies with JIS C 0806
 (Packaging of Electronic Components on Continuous Tapes).

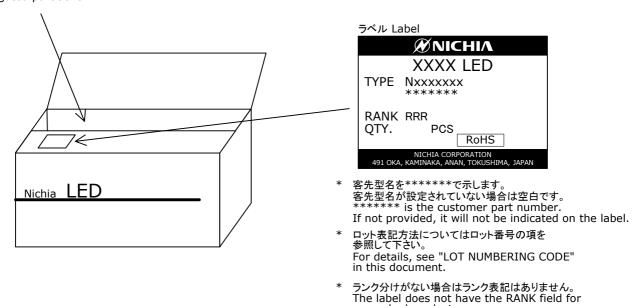
PACKAGING - TAPE & REEL

シリカゲルとともにリールをアルミ防湿袋に入れ、熱シールにより封をします。 Reels are shipped with desiccants in heat-sealed moisture-proof bags. Nxxxxxxx 管理番号 No. STS-DA7-0006C



アルミ防湿袋を並べて入れ、ダンボールで仕切ります。

Moisture-proof bags are packed in cardboard boxes with corrugated partitions.



un-ranked products.

- * 本製品はテーピングしたのち、輸送の衝撃から保護するためダンボールで梱包します。
 Products shipped on tape and reel are packed in a moisture-proof bag.
 They are shipped in cardboard boxes to protect them from external forces during transportation.
- * 取り扱いに際して、落下させたり、強い衝撃を与えたりしますと、製品を損傷させる原因になりますので注意して下さい。 Do not drop or expose the box to external forces as it may damage the products.
- * ダンボールには防水加工がされておりませんので、梱包箱が水に濡れないよう注意して下さい。 Do not expose to water. The box is not water-resistant.
- * 輸送、運搬に際して弊社よりの梱包状態あるいは同等の梱包を行って下さい。 Using the original package material or equivalent in transit is recommended.

LOT NUMBERING CODE

Lot Number is presented by using the following alphanumeric code.

YMxxxx - RRR

Y - Year

| Year | Y |
|------|---|
| 2009 | 9 |
| 2010 | А |
| 2011 | В |
| 2012 | С |
| 2013 | D |
| 2014 | Е |

M - Month

| Month | М | Month | М |
|-------|---|-------|---|
| 1 | 1 | 7 | 7 |
| 2 | 2 | 8 | 8 |
| 3 | 3 | 9 | 9 |
| 4 | 4 | 10 | Α |
| 5 | 5 | 11 | В |
| 6 | 6 | 12 | С |

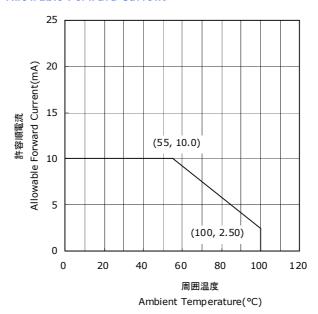
xxxx-Nichia's Product Number

RRR-Ranking by Color Coordinates, Ranking by Luminous Intensity

NHSx046x 管理番号 No. STS-DA7-0588A

周囲温度-許容順電流特性

Ambient Temperature vs Allowable Forward Current



デューティー比-許容順電流特性

Duty Ratio vs
Allowable Forward Current

TA=25°C

100

(VE) 100

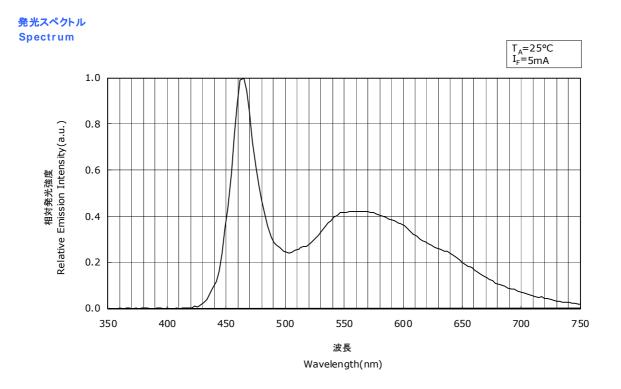
(RE) 100

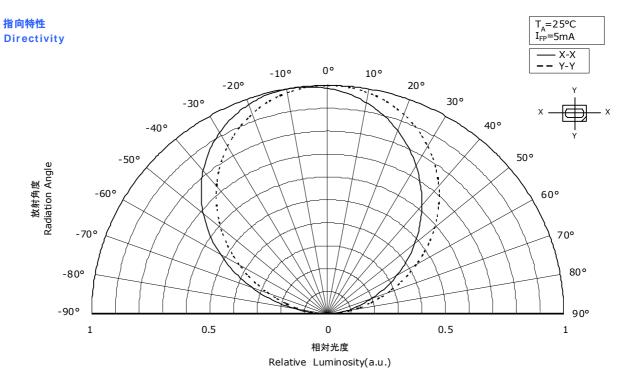
(WE) 100

Duty Ratio(%)

OPTICAL CHARACTERISTICS

* 本特性は参考です。 All characteristics shown are for reference only and are not guaranteed. NHSW046 管理番号 No. STS-DA7-0640A



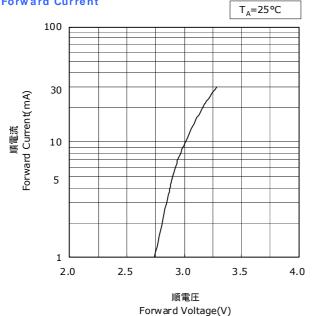


FORWARD CURRENT CHARACTERISTICS / TEMPERATURE CHARACTERISTICS

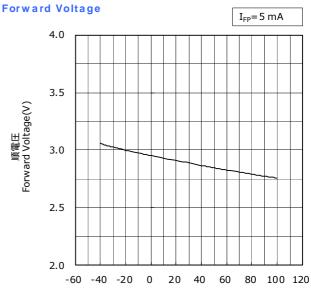
* 本特性は参考です。 All characteristics shown are for reference only and are not guaranteed. NHSW046 管理番号 No. STS-DA7-0641A

順電圧-順電流特性

Forward Voltage vs Forward Current



周囲温度-順電圧特性 Ambient Temperature vs

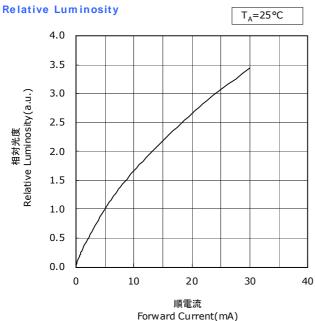


周囲温度

Ambient Temperature(°C)

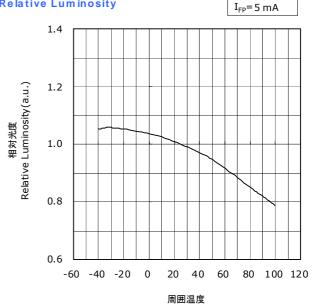
順電流-相対光度特性

Forward Current vs



周囲温度-相対光度特性

Ambient Temperature vs Relative Luminosity

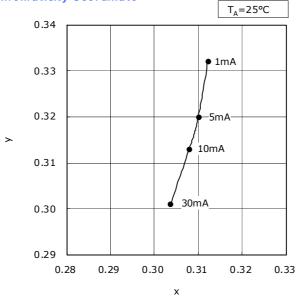


FORWARD CURRENT CHARACTERISTICS / TEMPERATURE CHARACTERISTICS

* 本特性は参考です。 All characteristics shown are for reference only and are not guaranteed. NHSW046 管理番号 No. STS-DA7-0642A

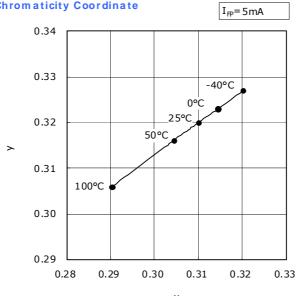
順電流-色度特性

Forward Current vs Chromaticity Coordinate



周囲温度-色度特性

Ambient Temperature vs Chromaticity Coordinate



RELIABILITY

(1) Tests and Results

| Test | Reference Standard | Test Conditions | Test Duration | Failure Criteria # | Units Failed/Tested |
|---|---------------------------|--|--|--------------------------|------------------------|
| Resistance to Soldering Heat (Dip Soldering) | JEITA ED-4701 300 301 | T _{sld} =260°C, 10sec, 1dip, Precondition: 30°C, 70%RH, 168hr | | #1 | 0/22 |
| Resistance to Soldering Heat (Reflow Soldering) | JEITA ED-4701 300 301 | T _{sld} =260°C, 10sec, 2reflows, Precondition: 30°C, 70%RH, 168hr | | #1 | 0/22 |
| Solderability (Dip/Reflow Soldering) | JEITA ED-4701 303 303A | T _{sld} =245±5°C, 5sec, Lead-free Solder(Sn-3.0Ag-0.5Cu) | ' ' | | 0/22 |
| Thermal Shock | JEITA ED-4701 300 307 | -40°C to 100°C, 1min dwell, 10sec transfer, Precondition: 30°C, 70%RH, 168hr | C to 100°C, 1min dwell, c transfer, 100cycles | | 0/100 |
| Temperature Cycle | JEITA ED-4701 100 105 | -40°C(30min)~25°C(5min)~ 100°C(30min)~25°C(5min) | C(5min)~ | | 0/100 |
| Moisture Resistance (Cyclic) | JEITA ED-4701 200 203 | 25°C~65°C~-10°C, 90%RH, 24hr per cycle | 10cycles | #1 | 0/100 |
| High Temperature Storage | JEITA ED-4701 200 201 | T _A =100°C | 1000hours | #1 | 0/100 |
| Temperature Humidity Storage | JEITA ED-4701 100 103 | T _A =60°C, RH=90% | 1000hours | #1 | 0/100 |
| Low Temperature Storage | JEITA ED-4701 200 202 | T _A =-40°C | 1000hours | #1 | 0/100 |
| Room Temperature Operating Life | | T _A =25°C, I _F =10mA | 1000hours | #2 | 0/100 |
| High Temperature Operating Life | | T _A =85°C, I _F =5mA | 1000hours | #2 | 0/100 |
| Temperature Humidity Operating Life | | 60°C, RH=90%, I _F =5mA | 1000hours | #2 | 0/100 |
| Low Temperature Operating Life | | T _A =-40°C, I _F =5mA | 1000hours | #2 | 0/100 |
| Permanence of Marking | JEITA ED-4701 500 501 | Isopropyl Alcohol, 23±5°C, Dipping Time: 5min | l 1time | | 0/22 |
| Vibration | JEITA ED-4701 400 403 | 200m/s², 100~2000~100Hz, 4cycles, 4min, each X, Y, Z | | #1 | 0/10 |
| Free Fall | | 3drops from a height of 75cm | | #1 | 0/10 |
| Electrostatic Discharges | JEITA ED-4701 300 304 | HBM, 2kV, $1.5k\Omega$, $100pF$, $3pulses$, alternately positive or negative | | #1 | 0/22 |

NOTES:

Measurements are performed after allowing the LEDs to return to room temperature.

(2) Failure Criteria

| Criteria # | Criteria # Items | | Failure Criteria | |
|------------------|-------------------------------------|---------------------|-----------------------------------|--|
| #1 | Forward Voltage(V _F) | I _F =5mA | >U.S.L.×1.1 | |
| | Luminous Intensity(I _v) | I _F =5mA | <l.s.l.×0.7< td=""></l.s.l.×0.7<> | |
| #2 | Forward Voltage(V _F) | I _F =5mA | >U.S.L.×1.1 | |
| | Luminous Intensity(I _v) | I _F =5mA | <l.s.l.×0.5< td=""></l.s.l.×0.5<> | |
| #3 Solderability | | - | Less than 95% solder coverage | |

U.S.L.: Upper Specification Limit L.S.L.: Lower Specification Limit

CAUTIONS

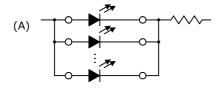
(1) Storage

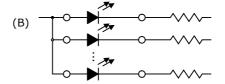
| Conditions | | Temperature | Humidity | Time |
|------------|-----------------------------|-------------|----------|----------------------------------|
| | Before Opening Aluminum Bag | ≤30°C | ≤90%RH | Within 1 Year from Delivery Date |
| Storage | After Opening Aluminum Bag | ≤30°C | ≤70%RH | ≤168hours |
| Baking | | 65±5°C | - | ≥24hours |

- Product complies with JEDEC MSL 3 or equivalent. See IPC/JEDEC STD-020 for moisture-sensitivity details.
- Absorbed moisture in LED packages can vaporize and expand during soldering, which can cause interface delamination
 and result in optical performance degradation. Products are packed in moisture-proof aluminum bags
 to minimize moisture absorption during transportation and storage.
 - Included silica gel desiccants change from blue to red if moisture had penetrated bags.
- After opening the moisture-proof aluminum bag, the products should go through the soldering process
 within the range of the conditions stated above. Unused remaining LEDs should be stored with silica gel desiccants
 in a hermetically sealed container, preferably the original moisture-proof bags for storage.
- After the "Period After Opening" storage time has been exceeded or silica gel desiccants are no longer blue, the products should be baked. Baking should only be done once.
- The leads or electrode pads (anode and cathode) of the product are plated with silver. Exposure to a corrosive environment
 might cause the silver plated the leads or electrode pads to tarnish, and thus leading to difficulties in soldering.
 If unused LEDs remain, they must be stored in a hermetically sealed container.
 Nichia recommends using the original moisture-proof bag for storage.
- Do not use sulfur-containing materials in commercial products. Some materials, such as seals and adhesives, may contain sulfur. The extremely corroded or contaminated plating of LEDs might cause an open circuit. Silicone rubber is recommended as a material for seals. Bear in mind, the use of silicones may lead to silicone contamination of electrical contacts inside the products, caused by low molecular weight volatile siloxane.
- To prevent water condensation, please avoid large temperature and humidity fluctuations for the storage conditions.

(2) Directions for Use

When designing a circuit, the current through each LED must not exceed the Absolute Maximum Rating.
 Operating at a constant current per LED is recommended. In case of operating at a constant voltage, Circuit B is recommended.
 If the LEDs are operated with constant voltage using Circuit A, the current through the LEDs may vary due to the variation in Forward Voltage characteristics of the LEDs.





- LEDs should be operated in forward bias. Driving circuits must not subject LEDs to either forward or reverse voltage while off.

 Continuous reverse voltage can cause migration and LED damage.
- ullet It is recommended to operate the LEDs at a current greater than 10% of the sorting current to stabilize the LED characteristics.
- For outdoor use, necessary measures should be taken to prevent water, moisture and salt air damage.

(3) Handling Precautions

- Do not handle LEDs with bare hands, it may contaminate the LED surface and affect optical characteristics.

 In the worst case, catastrophic failure from excess pressure through wire-bond breaks and package damage may result.
- When handling the product with tweezers, be careful not to apply excessive force to the resin.
 Otherwise, The resin can be cut, chipped, delaminate or deformed, causing wire-bond breaks and catastrophic failures.
- Dropping the product may cause damage.
- Do not stack assembled PCBs together. Failure to comply can cause the resin portion of the product to be cut, chipped, delaminated and/or deformed. It may cause wire to break, leading to catastrophic failures.

(4) Design Consideration

- PCB warpage after mounting the products onto a PCB can cause the package to break.
 - The LED should be placed in a way to minimize the stress on the LEDs due to PCB bow and twist.
- The position and orientation of the LEDs affect how much mechanical stress is exerted on the LEDs placed near the score lines.

 The LED should be placed in a way to minimize the stress on the LEDs due to board flexing.
- Board separation must be performed using special jigs, not using hands.

(5) Electrostatic Discharge (ESD)

• The products are sensitive to static electricity or surge voltage. ESD can damage a die and its reliability.

When handling the products, the following measures against electrostatic discharge are strongly recommended:

Eliminating the charge

Grounded wrist strap, ESD footwear, clothes, and floors

Grounded workstation equipment and tools

ESD table/shelf mat made of conductive materials

• Proper grounding is required for all devices, equipment, and machinery used in product assembly.

Surge protection should be considered when designing of commercial products.

• If tools or equipment contain insulating materials such as glass or plastic,

the following measures against electrostatic discharge are strongly recommended:

Dissipating static charge with conductive materials

Preventing charge generation with moisture

Neutralizing the charge with ionizers

• The customer is advised to check if the LEDs are damaged by ESD

when performing the characteristics inspection of the LEDs in the application.

Damage can be detected with a forward voltage measurement or a light-up test at low current (≤1mA).

• ESD damaged LEDs may have current flow at a low voltage or no longer illuminate at a low current.

Failure Criteria: V_F<2.0V at I_F=0.5mA

(6) Thermal Management

- Proper thermal management is an important when designing products with LEDs. LED die temperature is affected by PCB thermal resistance and LED spacing on the board. Please design products in a way that the LED die temperature does not exceed the maximum Junction Temperature (T_J).
- Drive current should be determined for the surrounding ambient temperature (TA) to dissipate the heat from the product.

(7) Cleaning

- If required, isopropyl alcohol (IPA) should be used. Other solvents may cause premature failure to the LEDs due to the damage to the resin portion. The effects of such solvents should be verified prior to use.

 In addition, the use of CFCs such as Freon is heavily regulated.
- Ultrasonic cleaning is not recommended since it may have adverse effects on the LEDs depending on the ultrasonic power and how LED is assembled.

If ultrasonic cleaning must be used, the customer is advised to make sure the LEDs will not be damaged prior to cleaning.

(8) Eye Safety

• In 2006, the International Electrical Commission (IEC) published IEC 62471:2006 Photobiological safety of lamps and lamp systems, which added LEDs in its scope.

On the other hand, the IEC 60825-1:2007 laser safety standard removed LEDs from its scope.

However, please be advised that some countries and regions have adopted standards

based on the IEC laser safety standard IEC 60825-1:20112001, which still includes LEDs in its scope.

Most of Nichia's LEDs can be classified as belonging into either the Exempt Group or Risk Group 1.

High-power LEDs, that emit light containing blue wavelengths, may be classified as Risk Group 2.

Please proceed with caution when viewing directly any LEDs driven at high current, or viewing LEDs with optical instruments which may greatly increase the damages to your eyes.

 Viewing a flashing light may cause eye discomfort. When incorporating the LED into your product, please be careful to avoid adverse effects on the human body caused by light stimulation.

(9) Others

- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances).
 Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control system, automobiles, traffic control equipment, life support systems and safety devices).
- The customer shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the customer shall inform Nichia directly before disassembling or analysis.
- Both the customers and Nichia will agree on official specifications of supplied products before a customer's volume production.
- Specifications and appearance subject to change for improvement without notice.